

Version with Markings to Show Changes Made

Claims 11 and 19 have been amended as outlined below, and new claims 23-32 have been added. The currently pending claims, including the aforementioned amendments, are as follows:

1 11. (Once Amended) An assembly comprising:

2 a circuit board;

3 an area array bonding site on a surface of the circuit board; and

4 a protective cover overlaying the bonding site, the protective cover being non-
5 conductive throughout at least a region thereof that overlays the bonding site, and the
6 protective cover removably registered to the bonding site by a plurality of posts secured to
7 one of the protective cover and the circuit board into a plurality of apertures disposed in
8 the other of the protective cover and the circuit board.

1 12. The assembly of claim 11, wherein the protective cover includes an adhesiveless
2 surface contacting the bonding site.

1 19. (Once Amended) A cover for protecting an area array bonding site on a surface of a
2 circuit board, the circuit board having a plurality of apertures, the cover comprising:

3 a base member having a first face and second face, the base member shaped to at
4 least correspond to said area array bonding site, and the base member being non-
5 conductive throughout at least a region thereof that is configured to overlay the bonding
6 site; and

7 a plurality of posts coupled to the first face and registered for said plurality of
8 apertures.

1 20. The cover of claim 19, wherein the first face of the base member further includes
2 a recess corresponding to said area array bonding site.

- 1 21. The cover of claim 19, further comprising:
2 a graspable extension coupled to the second face of the base member.
- 1 22. The cover of claim 19, wherein each of the plurality of posts includes a diametral
2 slot.
- 1 23. (New Claim) The assembly of claim 11, wherein the plurality of posts are secured to
2 the protective cover, and wherein the plurality of apertures are disposed in the circuit board.
- 1 24. (New Claim) The assembly of claim 11, wherein the protective cover is formed of a
2 non-conductive material.
- 1 25. (New Claim) The assembly of claim 24, wherein the protective cover is formed of
2 epoxy glass.
- 1 26. (New Claim) The assembly of claim 11, further comprising a graspable extension
2 disposed on a surface of the protective cover opposite that which overlays the bonding site.
- 1 27. (New Claim) The assembly of claim 11, wherein each of the plurality of posts
2 includes a diametral slot.
- 1 28. (New Claim) The assembly of claim 11, wherein the protective cover has a thickness
2 of about 0.006 to about 0.008 inches.
- 1 29. (New Claim) The assembly of claim 11, wherein the protective cover further includes
2 a recess overlaying the bonding site.

1 30. (New Claim) The cover of claim 19, wherein the base member is formed of a non-
2 conductive material.

1 31. (New Claim) The cover of claim 30, wherein the base member is formed of epoxy
2 glass.

1 32.(New Claim) The cover of claim 19, wherein the base member has a thickness of
2 about 0.006 to about 0.008 inches.